# **ULSI** Technology

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Acknowledgments begin on page 724 and appear on this page by reference.

This book is printed on acid-free paper.

234567890 DOC DOC 909876

ISBN 0-07-063062-3

This book was set in Times Roman by Publication Services, Inc.
The editors were Lynn Cox and John M. Morriss;
the production supervisor was Denise L. Puryean.
The cover was designed by Farenga Design Group.
Project supervision was done by Publication Services, Inc.
R. R. Donnelley & Sons Company was printer and binder.

Cover photo: Electron micrograph of contact holes filled with CVD tungsten plugs (see Chapter 8). The diameter is 0.25 micron. Courtesy of the National Nano Device Laboratories, National Science Council, R.O.C.

Library of Congress Catalog Card Number: 95-81366



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